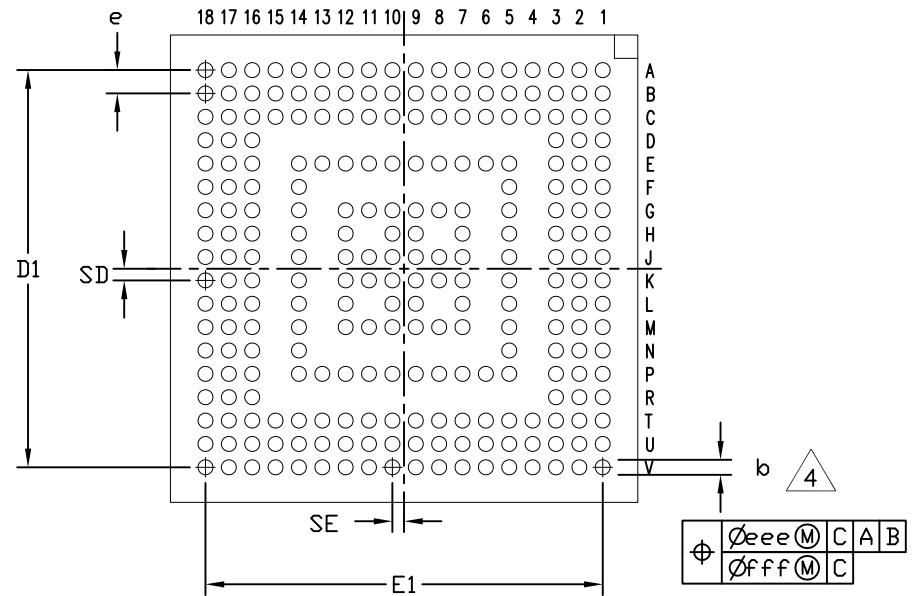
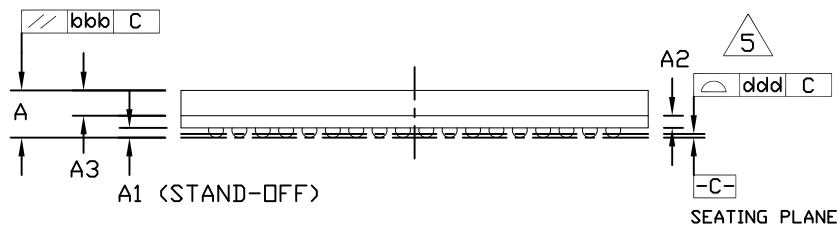


TOP VIEW



BOTTOM VIEW



SIDE VIEW

-DRAWING NOT TO SCALE-

MAXIM

TITLE:
PACKAGE OUTLINE, 248 BALLS
CTBGA, 10x10x1.1mm, 0.5mm PITCH

APPROVAL	DOCUMENT CONTROL NO. 21-0503	REV. B	1/2
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NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. 'e' REPRESENTS THE BASIC SOLDER BALL GRID PITCH.
3. 'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE AND SYMBOL 'N' IS THE NUMBER OF BALLS AFTER DEPOPULATING.
4. 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER AFTER REFLOW PARALLEL TO PRIMARY DATUM [-C-].
5. DIMENSION 'ddd' IS MEASURED PARALLEL TO PRIMARY DATUM [-C-].
6. PRIMARY DATUM [-C-] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
7. PACKAGE SURFACE SHALL BE MATTE FINISH.
8. SUBSTRATE MATERIAL BASE IS BT RESIN.
9. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
10. MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
11. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC# 10-0131.
12. DRAWING CONFORMS TO JEDEC MO-216.
13. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFree (+) PACKAGE CODES.

DIMENSIONS			
REF.	MIN.	NOM.	MAX.
A	1.00	--	1.20
A1	0.16	0.21	0.26
A2	0.26 REF.		
A3	0.54 REF.		
D	10.00 BSC.		
D1	8.50 BSC		
E	10.00 BSC		
E1	8.50 BSC		
b	0.27	--	0.37
e	0.50 BSC		
SD	0.25 BSC		
SE	0.25 BSC		
aaa	0.10		
bbb	0.10		
ddd	0.08		
eee	0.15		
fff	0.08		
N	248		
PKGCODES: X24800-1			

-DRAWING NOT TO SCALE-

			
TITLE: PACKAGE OUTLINE, 248 BALLS CTBGA, 10x10x1.1mm, 0.5mm PITCH			
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